

# bq29209-Q1 Voltage Protection with Automatic Cell Balance for 2-Series Cell Li-Ion Batteries

## 1 Features

- 2-Series Cell Secondary Protection
- Automatic Cell Imbalance Correction with External Enable Control
  - $\pm 30$ -mV Enable, 0-mV Disable Thresholds Typical
- External Capacitor-Controlled Delay Timer
- External Resistor-Controlled Cell Balance Current
- Low Power Consumption  $I_{CC} < 3 \mu\text{A}$  Typical ( $V_{CELL(ALL)} < V_{PROTECT}$ )
- Internal Cell Balancing Handles Current up to 15 mA
- External Cell Balancing Mode Supported
- High-Accuracy Overvoltage Protection:
  - $\pm 25$  mV with  $T_A = 0^\circ\text{C}$  to  $60^\circ\text{C}$
- Fixed Overvoltage Protection Threshold: 4.30 V
- Small 8L DRB Package
- Automotive-Qualified AEC Q100 Grade Two

## 2 Applications

- 2<sup>nd</sup> Level Protection in Li-Ion Battery Packs
  - Emergency Call (eCall)
  - Netbook Computers
  - Power Tools
  - Portable Equipment and Instrumentation
  - Battery Backup Systems

## 3 Description

The bq29209-Q1 device is a secondary overvoltage protection IC for 2-series cell lithium-ion battery packs that incorporates a high-accuracy precision overvoltage detection circuit and automatic cell imbalance correction.

The voltage of each cell in a 2-series cell battery pack is compared to a factory programmed internal reference voltage. If either cell reaches an overvoltage condition, the OUT pin changes from low to high state.

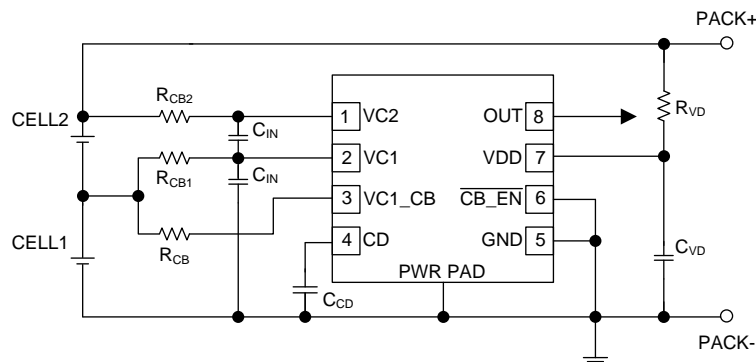
The bq29209-Q1 can perform automatic voltage-based cell imbalance correction. Balancing can start when the cell voltages are different by nominally 30 mV or more and stops when the difference is nominally 0 mV. Cell balancing is enabled and disabled by the  $\overline{\text{CB\_EN}}$  pin.

### Device Information<sup>(1)</sup>

PART NUMBER	PACKAGE	BODY SIZE (NOM)
bq29209-Q1	VSON (8)	3.00 mm x 3.00 mm

(1) For all available packages, see the orderable addendum at the end of the datasheet.

### Simplified Schematic



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## 4 Revision History

### Changes from Original (June 2015) to Revision A

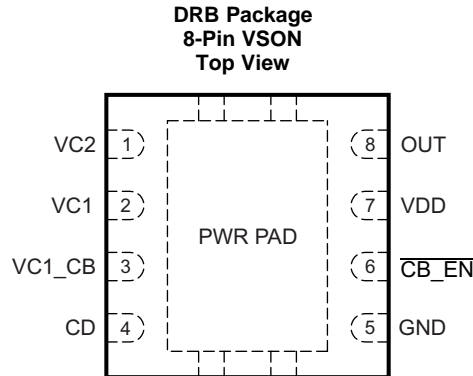
**Page**

• Changed resistor $R_{VD}$ location, added PACK+ and PACK- in the <i>Simplified Schematic</i> image .....	<b>1</b>
• Deleted the Lead Temperature (soldering) from the <i>Absolute Maximum Ratings</i> table .....	<b>3</b>
• Changed resistor $R_{VD}$ location in <a href="#">Figure 9</a> .....	<b>12</b>
• Added title to <a href="#">Table 1</a> .....	<b>12</b>
• Changed resistor $R_{VD}$ location, added PACK+ and PACK- in <a href="#">Figure 11</a> .....	<b>13</b>

## 5 Device Options

T <sub>A</sub>	PART NUMBER	OVP
–40°C to +105°C	BQ29209-Q1	4.3 V

## 6 Pin Configuration and Functions



**Pin Functions**

PIN		DESCRIPTION
NAME	NO.	
$\overline{\text{CB\_EN}}$	6	Cell balance enable
CD	4	Connection to external capacitor for programmable delay time
GND	5	Ground pin
OUT	8	Output
Thermal Pad	PWR PAD	GND pin to be connected to the PWRPAD on the printed circuit board for proper operation
VC1	2	Sense voltage input for bottom cell
VC1_CB	3	Cell balance input for bottom cell
VC2	1	Sense voltage input for top cell
VDD	7	Power supply

## 7 Specifications

### 7.1 Absolute Maximum Ratings

Over-operating free-air temperature range (unless otherwise noted)<sup>(1)</sup>

		MIN	MAX	UNIT
Supply voltage range, V <sub>MAX</sub>	VDD–GND	–0.3	16	V
Input voltage range, V <sub>IN</sub>	VC2–GND, VC1–GND	–0.3	16	V
	VC2–VC1, CD–GND	–0.3	8	V
	$\overline{\text{CB\_EN}}$ –GND	–0.3	16	V
Output voltage range, V <sub>OUT</sub>	OUT–GND	–0.3	16	V
Continuous total power dissipation, P <sub>TOT</sub>	See <a href="#">Thermal Information</a> .			
Storage temperature, T <sub>stg</sub>		–65	150	°C

(1) Stresses beyond those listed under *Absolute Maximum Ratings* may cause permanent damage to the device. These are stress ratings only, which do not imply functional operation of the device at these or any other conditions beyond those indicated under *Recommended Operating Conditions*. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

## 7.2 ESD Ratings

			VALUE	UNIT	
V <sub>(ESD)</sub>	Electrostatic discharge	Human-body model (HBM), per AEC Q100-002 <sup>(1)</sup>	±2000	V	
		Charged-device model (CDM), per AEC Q100-011	All pins		±500
			Corner pins (VC2, CD, OUT, and GND)		±750

(1) AEC Q100-002 indicates that HBM stressing shall be in accordance with the ANSI/ESDA/JEDEC JS-001 specification.

## 7.3 Recommended Operating Conditions

		MIN	NOM	MAX	UNIT
Supply voltage, VDD		4		10	V
Input voltage range	VC2–VC1, VC1–GND	0		5	V
Delay time capacitance, t <sub>d(CD)</sub>	C <sub>CD</sub> (See <a href="#">Figure 9</a> .)		0.1		μF
Voltage monitor filter resistance	R <sub>IN</sub> (See <a href="#">Figure 9</a> .)	100	1K		Ω
Voltage monitor filter capacitance	C <sub>IN</sub> (See <a href="#">Figure 9</a> .)	0.01	0.1		μF
Supply voltage filter resistance	R <sub>VD</sub> (See <a href="#">Figure 9</a> .)		100	1K	Ω
Supply voltage filter capacitance	C <sub>VD</sub> (See <a href="#">Figure 9</a> .)		0.1		μF
Cell balance resistance	R <sub>CB</sub> (See <a href="#">Figure 9</a> and <a href="#">Protection (OUT) Timing</a> .)	100		4.7K	Ω
Operating ambient temperature range, T <sub>A</sub>		–40		105	°C

## 7.4 Thermal Information

THERMAL METRIC <sup>(1)</sup>		bq29209-Q1			UNIT
		DRB			
		8 PINS			
R <sub>θJA</sub>	Junction-to-ambient thermal resistance	50.5			°C/W
R <sub>θJC(top)</sub>	Junction-to-case(top) thermal resistance	25.1			°C/W
R <sub>θJB</sub>	Junction-to-board thermal resistance	19.3			°C/W
Ψ <sub>JT</sub>	Junction-to-top characterization parameter	0.7			°C/W
Ψ <sub>JB</sub>	Junction-to-board characterization parameter	18.9			°C/W
R <sub>θJC(bot)</sub>	Junction-to-case(bottom) thermal resistance	5.2			°C/W

(1) For more information about traditional and new thermal metrics, see the *Semiconductor and IC Package Thermal Metrics* application report, [SPRA953](#).

## 7.5 Electrical Characteristics

Typical values stated where T<sub>A</sub> = 25°C and VDD = 7.2 V. Minimum and maximum values stated where T<sub>A</sub> = –40°C to 105°C and VDD = 4 V to 10 V (unless otherwise noted).

PARAMETER	TEST CONDITIONS	MIN	TYP	MAX	UNIT
V <sub>PROTECT</sub>	Overvoltage detection voltage		4.3		V
V <sub>HYS</sub>	Overvoltage detection hysteresis	200	300	400	mV
V <sub>OA</sub>	Overvoltage detection accuracy	T <sub>A</sub> = 25°C		10	mV
V <sub>OA_DRIFT</sub>	Overvoltage threshold temperature drift	T <sub>A</sub> = 0°C to 60°C		0.4	mV/°C
		T <sub>A</sub> = –40°C to 110°C		0.6	
X <sub>DELAY</sub>	Overvoltage delay time scale factor	T <sub>A</sub> = 0°C to 60°C Note: Does not include external capacitor variation.		12	s/μF
		T <sub>A</sub> = –40°C to 110°C Note: Does not include external capacitor variation.		13.5	

## Electrical Characteristics (continued)

Typical values stated where  $T_A = 25^\circ\text{C}$  and  $V_{DD} = 7.2\text{ V}$ . Minimum and maximum values stated where  $T_A = -40^\circ\text{C}$  to  $105^\circ\text{C}$  and  $V_{DD} = 4\text{ V}$  to  $10\text{ V}$  (unless otherwise noted).

PARAMETER		TEST CONDITIONS	MIN	TYP	MAX	UNIT
$X_{\text{DELAY\_CTM}}^{(1)}$	Overvoltage delay time scale factor in Customer Test Mode			0.08		s/ $\mu\text{F}$
$I_{\text{CD(CHG)}}$	Overvoltage detection charging current			150		nA
$I_{\text{CD(DSG)}}$	Overvoltage detection discharging current			60		$\mu\text{A}$
$V_{\text{CD}}$	Overvoltage detection external capacitor comparator threshold			1.2		V
$I_{\text{CC}}$	Supply current	$(V_{\text{C2}}-V_{\text{C1}}) = (V_{\text{C1}}-\text{GND}) = 3.5\text{ V}$ (See <a href="#">Figure 7.</a> )		3	6	$\mu\text{A}$
$V_{\text{OUT}}$	OUT pin drive voltage	$(V_{\text{C2}}-V_{\text{C1}})$ or $(V_{\text{C1}}-\text{GND}) > V_{\text{PROTECT}}$ , $V_{\text{DD}} = 10\text{ V}$ , $I_{\text{OH}} = 0$	6	8.25	9.5	V
		$(V_{\text{C2}}-V_{\text{C1}})$ or $(V_{\text{C1}}-\text{GND}) = V_{\text{PROTECT}}$ , $V_{\text{DD}} = V_{\text{PROTECT}}$ , $I_{\text{OH}} = -100\text{ }\mu\text{A}$ , $T_A = 0^\circ\text{C}$ to $60^\circ\text{C}$	1.75	2.5		V
		$(V_{\text{C2}}-V_{\text{C1}})$ and $(V_{\text{C1}}-\text{GND}) < V_{\text{PROTECT}}$ , $I_{\text{OL}} = 100\text{ }\mu\text{A}$ , $T_A = 25^\circ\text{C}$			200	mV
		$(V_{\text{C2}}-V_{\text{C1}})$ and $(V_{\text{C1}}-\text{GND}) < V_{\text{PROTECT}}$ , $I_{\text{OL}} = 0\text{ }\mu\text{A}$ , $T_A = 25^\circ\text{C}$		0	10	mV
		$V_{\text{C2}} = V_{\text{C1}} = V_{\text{DD}} = 4\text{ V}$ , $I_{\text{OL}} = 100\text{ }\mu\text{A}$			200	mV
$I_{\text{OH}}$	High-level output current	$\text{OUT} = 1.75\text{ V}$ , $(V_{\text{C2}}-V_{\text{C1}})$ or $(V_{\text{C1}}-\text{GND}) = V_{\text{PROTECT}}$ , $V_{\text{DD}} = V_{\text{PROTECT}}$ to $10\text{ V}$ , $T_A = 0^\circ\text{C}$ to $60^\circ\text{C}$	-100			$\mu\text{A}$
$I_{\text{OL}}$	Low-level output current	$\text{OUT} = 0.05\text{ V}$ , $(V_{\text{C2}}-V_{\text{C1}})$ or $(V_{\text{C1}}-\text{GND}) < V_{\text{PROTECT}}$ , $V_{\text{DD}} = V_{\text{PROTECT}}$ to $10\text{ V}$ , $T_A = 0^\circ\text{C}$ to $60^\circ\text{C}$	30		85	$\mu\text{A}$
$I_{\text{OH\_ZV}}$	High-level short-circuit output current	$\text{OUT} = 0\text{ V}$ , $(V_{\text{C2}}-V_{\text{C1}}) = (V_{\text{C1}}-\text{GND}) = V_{\text{PROTECT}}$ , $V_{\text{DD}} = 4$ to $10\text{ V}$			-8	mA
$I_{\text{IN}}$	Input current at VCx pins	Measured at VC1, $(V_{\text{C2}}-V_{\text{C1}}) = (V_{\text{C1}}-\text{GND}) = 3.5\text{ V}$ , $T_A = 0^\circ\text{C}$ to $60^\circ\text{C}$ (See <a href="#">Figure 7.</a> )	-0.2		0.2	$\mu\text{A}$
		Measured at VC2, $(V_{\text{C2}}-V_{\text{C1}}) = (V_{\text{C1}}-\text{GND}) = 3.5\text{ V}$ , $T_A = 0^\circ\text{C}$ to $60^\circ\text{C}$ (See <a href="#">Figure 7.</a> )			2.5	$\mu\text{A}$
$V_{\text{MM\_DET\_ON}}$	Cell mismatch detection threshold for turning ON	$(V_{\text{C2}}-V_{\text{C1}})$ versus $(V_{\text{C1}}-\text{GND})$ and vice-versa when cell balancing is enabled. $V_{\text{C2}} = V_{\text{DD}} = 7.6\text{ V}$	17	30	45	mV
$V_{\text{MM\_DET\_OFF}}$	Cell mismatch detection threshold for turning OFF	Delta between $(V_{\text{C2}}-V_{\text{C1}})$ and $(V_{\text{C1}}-\text{GND})$ when cell balancing is disabled. $V_{\text{C2}} = V_{\text{DD}} = 7.6\text{ V}$	-9	0	9	mV
$V_{\text{CB\_EN\_ON}}$	Cell balance enable ON threshold	Active LOW pin at $\overline{\text{CB\_EN}}$			1	V
$V_{\text{CB\_EN\_OFF}}$	Cell balance enable OFF threshold	Active HIGH at $\overline{\text{CB\_EN}}$	2.2			V
$I_{\text{CB\_EN}}$	Cell balance enable ON input current	$\overline{\text{CB\_EN}} = \text{GND}$ (See <a href="#">Figure 8.</a> )			0.2	$\mu\text{A}$
$R_{\text{CB1}}$	Internal cell balance switch resistance	$\overline{\text{CB\_EN}} = \text{GND}$				$\Omega$
$R_{\text{CB2}}$	Internal cell balance switch resistance	$\overline{\text{CB\_EN}} = \text{GND}$				$\Omega$

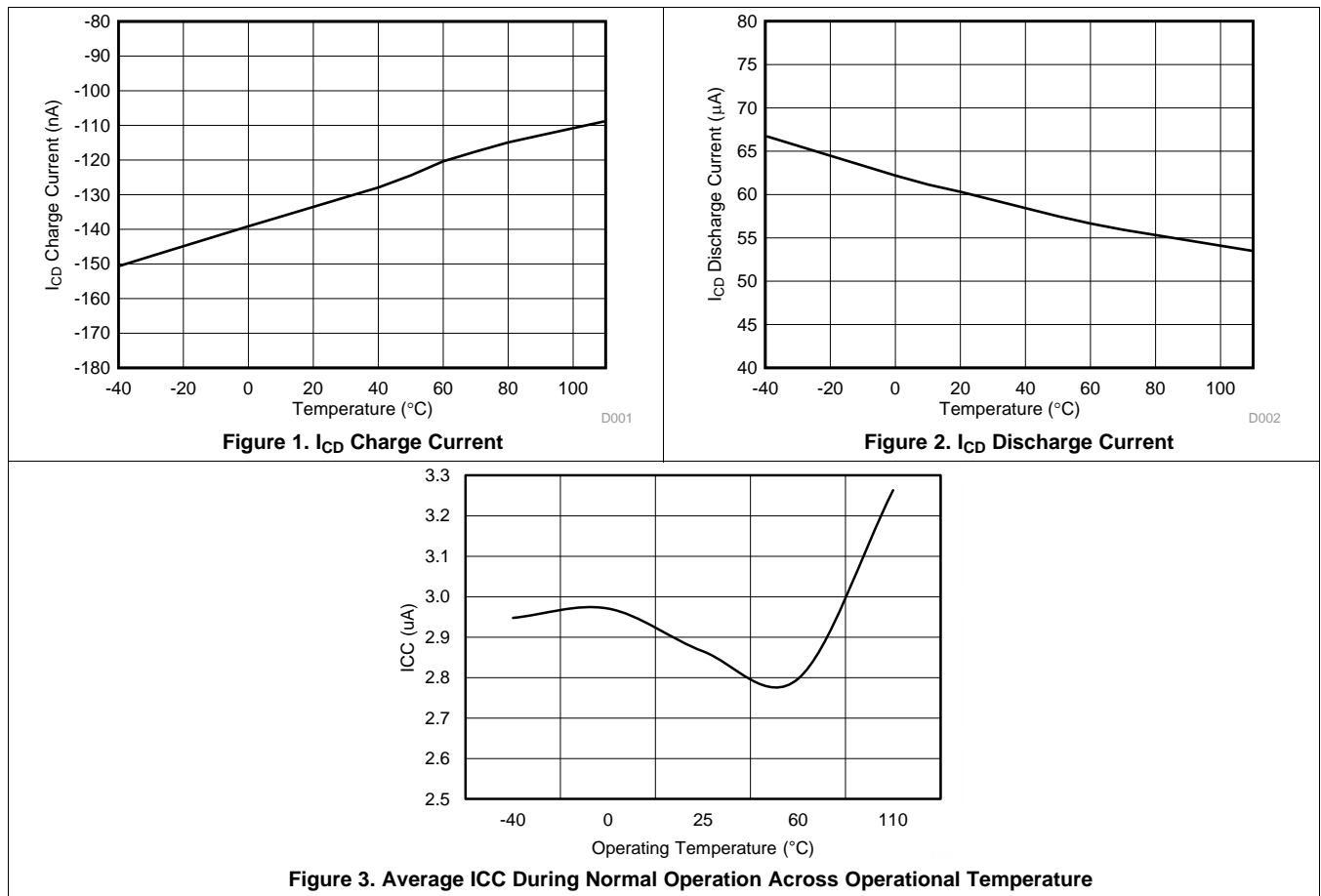
(1) Specified by design. Not 100% tested in production.

## 7.6 Recommended Cell Balancing Configurations

Typical values stated where  $T_A = 25^\circ\text{C}$  and  $(VC2-VC1)$ ,  $(VC1-GND) = 3.8\text{ V}$ . Minimum and maximum values stated where  $T_A = -40^\circ\text{C}$  to  $105^\circ\text{C}$ ,  $VDD = 4\text{ V}$  to  $10\text{ V}$ , and  $(VC2-VC1)$ ,  $(VC1-GND) = 3\text{ V}$  to  $4.2\text{ V}$ . All values assume recommended supply voltage filter resistance  $R_{VD}$  of  $100\ \Omega$  and 5% accurate or better cell balance resistor  $R_{CB}$ .

		MIN	NOM	MAX	UNIT
$I_{CB}$	Cell balance input current				mA
	$R_{CB} = 4700\ \Omega$	0.5	0.75	1	
	$R_{CB} = 2200\ \Omega$	1	1.5	2	
	$R_{CB} = 910\ \Omega$	2	3	4	
	$R_{CB} = 560\ \Omega$	3	4.5	6	
	$R_{CB} = 360\ \Omega$	3.5	6	8.5	
	$R_{CB} = 240\ \Omega$	4	7.5	11	
$R_{CB} = 120\ \Omega$	5	10	15		

## 7.7 Typical Characteristics



## 8 Detailed Description

### 8.1 Overview

The bq29209-Q1 provides overvoltage protection and cell balancing for 2-series cell lithium-ion battery packs.

#### 8.1.1 Voltage Protection

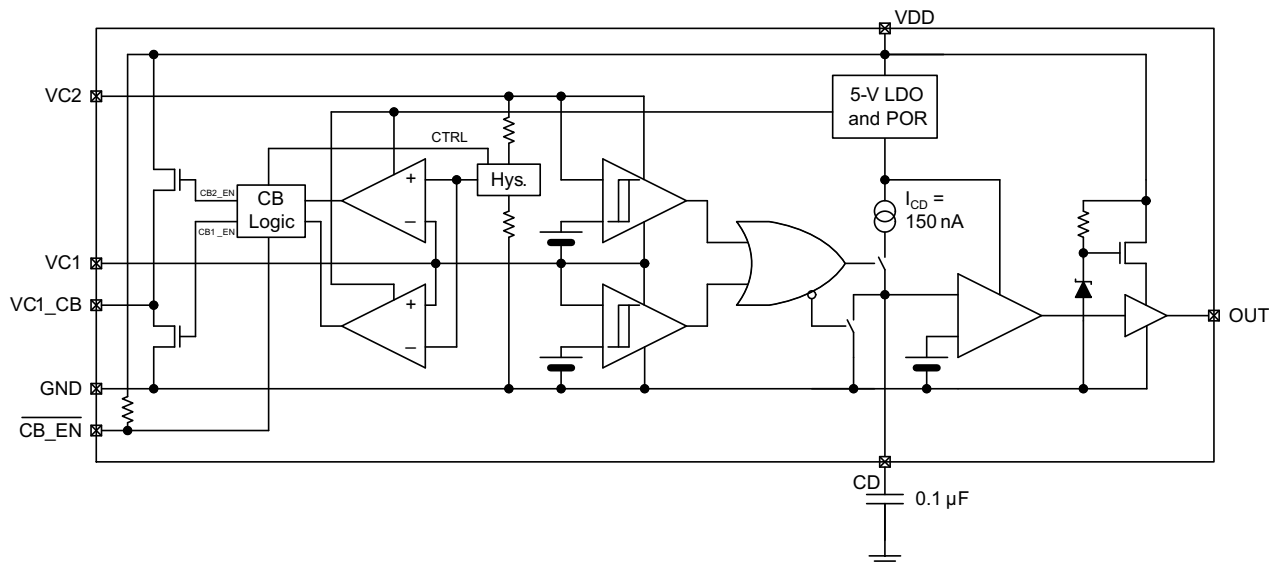
Each cell voltage is continuously compared to a factory configured internal reference threshold. If either cell reaches an overvoltage condition, the bq29209-Q1 device starts a timer that provides a delay proportional to the capacitance on the CD pin. Upon expiration of the internal timer, the OUT pin changes from a low to high state.

#### 8.1.2 Cell Balancing

If enabled, the bq29209-Q1 performs automatic cell-balance correction where the two cells are automatically corrected for voltage imbalance by loading the cell with the higher voltage with a small balancing current. When the cells are measured to be equal within nominally 0 mV, the load current is removed. It will be re-applied if the imbalance exceeds nominally 30 mV. The cell mismatch correction circuitry is enabled by pulling the CB\_EN pin low, and disabled when CB\_EN is pulled to greater than 2.2 V, for example, VDD.

If the internal cell balancing current of up to 15 mA is insufficient, the bq29209-Q1 may be configured via external circuitry to support much higher external cell balancing current.

### 8.2 Functional Block Diagram



### 8.3 Feature Description

#### 8.3.1 Protection (OUT) Timing

Sizing the external capacitor is based on the desired delay time as follows:

$$C_{CD} = \frac{t_d}{X_{DELAY}}$$

Where  $t_d$  is the desired delay time and  $X_{DELAY}$  is the overvoltage delay time scale factor, expressed in seconds per microFarad.  $X_{DELAY}$  is nominally 9 s/µF. For example, if a nominal delay of 3 seconds is desired, use a  $C_{CD}$  capacitor that is 3 s / 9 s/µF = 0.33 µF.

The delay time is calculated as follows:

$$t_d = C_{CD} \times X_{DELAY}$$

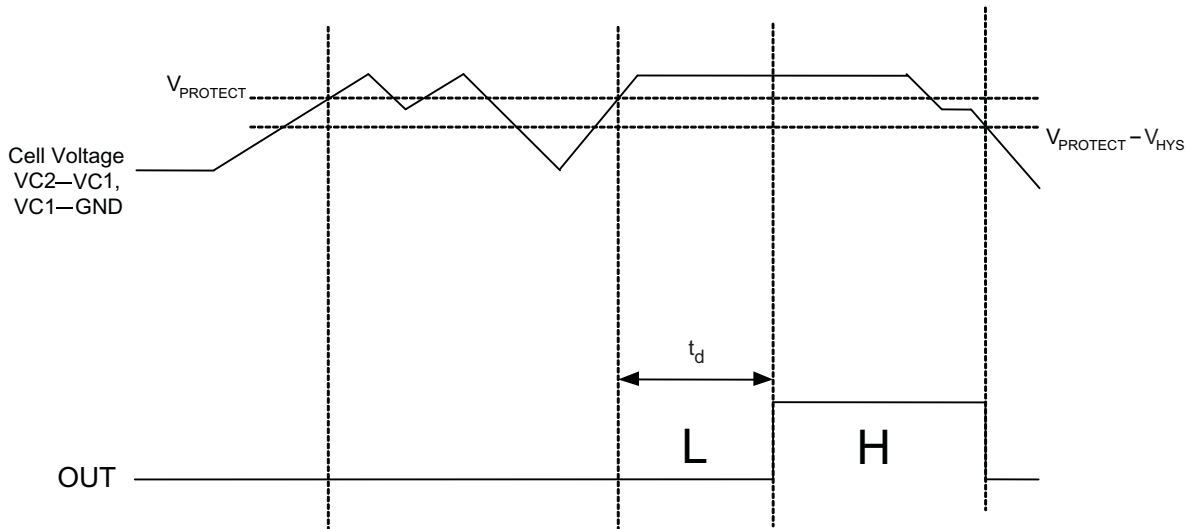
## Feature Description (continued)

If the cell overvoltage condition is removed before the external capacitor reaches the reference voltage, the internal current source is disabled and an internal discharge block is employed to discharge the external capacitor down to 0 V. In this instance, the OUT pin remains in a low state.

### 8.3.2 Cell Voltage > $V_{\text{PROTECT}}$

When one or both of the cell voltages rises above  $V_{\text{PROTECT}}$ , the internal comparator is tripped, and the delay begins to count to  $t_d$ . If the input remains above  $V_{\text{PROTECT}}$  for the duration of  $t_d$ , the bq29209-Q1 output changes from a low to a high state, by means of an internal pull-up network, to a regulated voltage of no more than 9.5 V when  $I_{\text{OH}} = 0$  mA.

The external delay capacitor should charge up to no more than the internal LDO voltage (approximately 5 V typically), and will fully discharge in approximately under 100 ms when the overvoltage condition is removed.



**Figure 4. Timing for Overvoltage Sensing**

### 8.3.3 Cell Connection Sequence

**NOTE**

Before connecting the cells, populate the overvoltage delay timing capacitor,  $C_{\text{CD}}$ .

The recommended cell connection sequence begins from the bottom of the stack, as follows:

1. GND
2. VC1
3. VC2

While not advised, connecting the cells in a sequence other than that described above does not result in errant activity on the OUT pin. For example:

1. GND
2. VC2 or VC1
3. Remaining VCx pin

### 8.3.4 Cell Balance Enable Control

To avoid prematurely discharging the cells, it is recommended to turn off (pull high) the active-low Cell Balance Enable Control pin at lower State of Charge (SOC) levels.



## Feature Description (continued)

### 8.3.5 Cell Balance Configuration

The cell balancing current may be calculated as follows:

For Cell 1 (VC1–GND) balancing current,  $I_{CB1}$ :

$$I_{CB1} = \frac{VC1}{R_{CB} + R_{CB1}} \quad (1)$$

For Cell 2 (VC2–VC1) balancing current,  $I_{CB2}$ :

$$I_{CB2} = \frac{(VC2 - VC1)}{(R_{CB} + R_{VD}) + R_{CB2}} \quad (2)$$

Where:

RCB = resistor connected between the top of Cell 1 and the VC1\_CB

RCB1 = resistor connected between the top of Cell 1 and the VC1

RCB2 = resistor connected between the top of Cell 2 and the VC2

RVD = resistor connected between the top of Cell 2 and the VDD

### 8.3.6 Cell Imbalance Auto-Detection (Via Cell Voltage)

The  $V_{MM\_DET\_ON}$  and  $V_{MM\_DET\_OFF}$  specifications are calibrated where  $VDD = VC2 = 7.6$  V and  $VC1 = 3.8$  V. The recommended range of cell balancing is  $VC2$  and  $VDD$  between 6.0 V and 8.4 V, and  $VC1$  between 3 V and 4.2 V. Below  $VDD = 6$  V, it is recommended to pull  $\overline{CB\_EN}$  high to disable the cell balancing function.

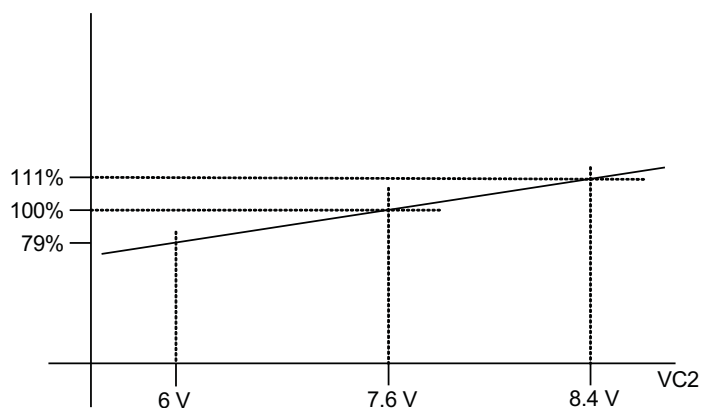


Figure 5.  $V_{MM\_DET\_ON}$  and  $V_{MM\_DET\_OFF}$  Threshold

### 8.3.7 Customer Test Mode

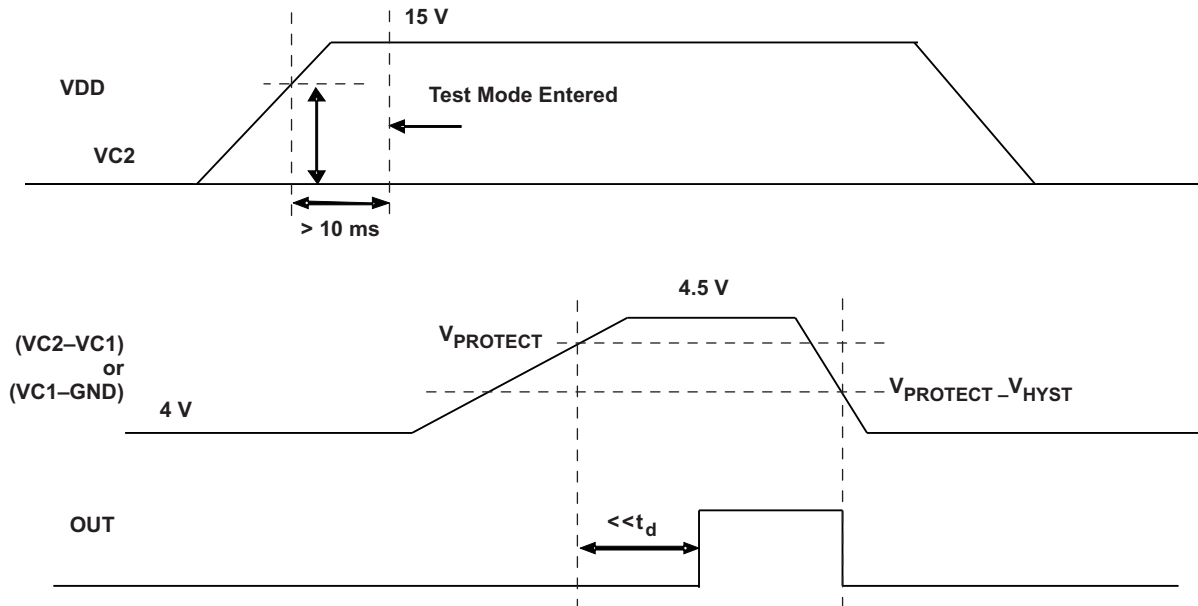
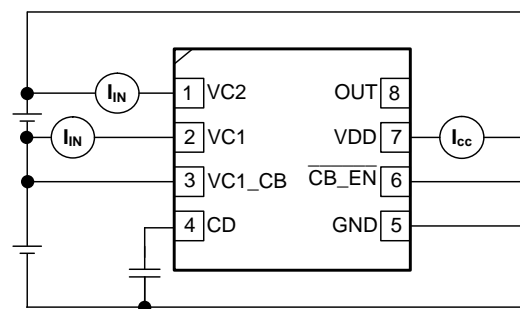
Customer Test Mode (CTM) helps to greatly reduce the overvoltage detection delay time and enable quicker customer production testing. This mode is intended for quick-pass board-level verification tests, and, as such, individual cell overvoltage levels may deviate slightly from the specifications ( $V_{PROTECT}$ ,  $V_{OA}$ ). If accurate overvoltage thresholds are to be tested, use the standard delay settings that are intended for normal use.

To enter CTM,  $VDD$  should be set to approximately 9.5 V higher than  $VC2$ . When CTM is entered, the device switches from the normal overvoltage delay time scale factor,  $X_{DELAY}$ , to a significantly reduced factor of approximately 0.08, thereby reducing the delay time during an overvoltage condition.

**Feature Description (continued)**
**CAUTION**

Avoid exceeding any Absolute Maximum Voltages on any pins when placing the part into CTM. Also, avoid exceeding absolute maximum voltages for the individual cell voltages (VC1–GND) and (VC2–VC1). Stressing the pins beyond the rated limits may cause permanent damage to the device.

To exit CTM, power off the device and then power it back on.


**Figure 6. Voltage Test Limits**
**8.3.8 Test Conditions**

**Figure 7.  $I_{CC}$ ,  $I_{IN}$  Measurement**

## Feature Description (continued)

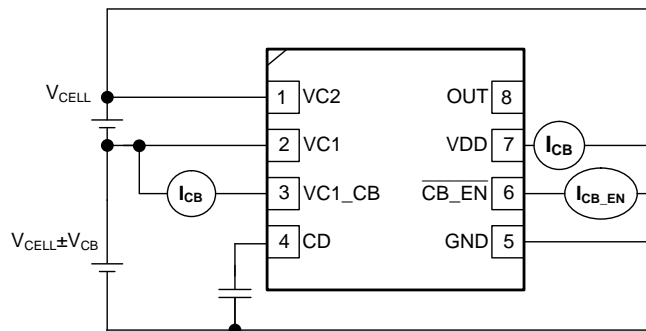


Figure 8.  $I_{CB}$  Measurement

### 8.4 Device Functional Modes

This device monitors the voltage of the cells connected to the VCx pins and depending on these voltages and the overall battery voltage at VDD the device enters different operating modes.

#### 8.4.1 NORMAL Mode

The device is operating in NORMAL mode when the cell voltage range is between the over-charge detection threshold ( $V_{PROTECT}$ ) and the minimum supply voltage.

If this condition is satisfied, the device turns OFF the OUT pin.

#### 8.4.2 PROTECTION Mode

The device is operating in PROTECTION mode when the cell over voltage protection feature has been triggered. See [Cell Voltage >  \$V\_{PROTECT}\$](#)  for more details on this feature.

If this condition is satisfied, the device turns ON the OUT pin.

## 9 Application and Implementation

### NOTE

Information in the following applications sections is not part of the TI component specification, and TI does not warrant its accuracy or completeness. TI's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

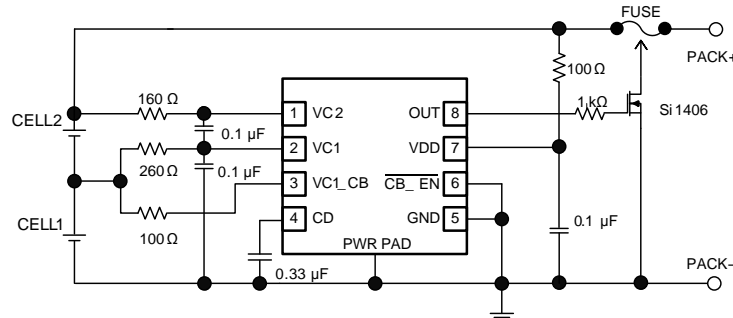
### 9.1 Application Information

The bq29209-Q1 is designed to be used in 2-series Li-Ion battery packs and with the option to include voltage-based cell balancing. The number of parallel cells or the overall capacity of the battery only affects the cell balancing circuit due to the level of potential imbalance that needs to be corrected.

### 9.2 Typical Applications

#### 9.2.1 Battery Connection

Figure 9 shows the configuration for the 2-series cell battery connection with cell balancing enabled.



**Figure 9. 2-Series Cell Configuration**

#### 9.2.1.1 Design Requirements

For this design example, use the parameters listed in Table 1.

**Table 1. Design Parameters**

DESIGN PARAMETER	EXAMPLE VALUE at $T_A = 25^\circ\text{C}$
Input voltage range	4 V to 10 V
Overvoltage Protection (OVT)	4.3 V
Overvoltage detection delay time	3 s
Overvoltage detection delay timer capacitor	0.33 $\mu\text{F}$
Cell Balancing Enabled	Yes
Cell Balancing Current, ICB1 and ICB2	10 mA
Cell Balancing Resistors, RCB, RCB1, RCB2 and RVD	RCB = 100 $\Omega$ , RCB1 = 260 $\Omega$ , RCB2 = 160 $\Omega$ , RVD = 100 $\Omega$

#### 9.2.1.2 Detailed Design Procedure

The bq29209-Q1 has limited features but there are some key calculations to be made when selecting external component values.

- Calculate the required CCD capacitor value for the voltage protection delay time. Care should be taken to evaluate the tolerances of the capacitor and the bq29209-Q1 to ensure system specifications are met.
- Calculate the cell balancing resistor values to provide a suitable level of balancing current that will, at a minimum, counter act an increase in imbalance during normal operation of the battery. Care should be taken to ensure any connectivity resistance is also considered as this will also reduce the balancing current level.

### 9.2.1.3 Application Curve

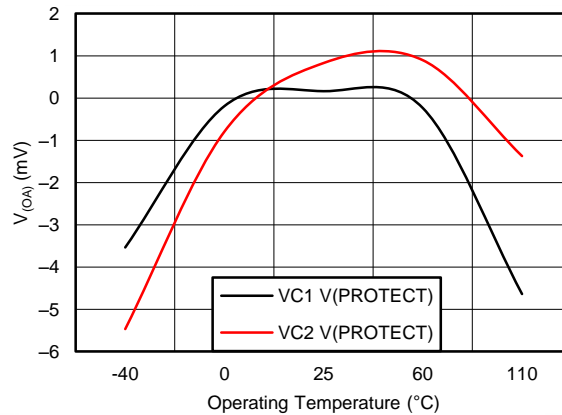


Figure 10. Average  $V_{\text{PROTECT}}$  Accuracy ( $V_{\text{OA}}$ ) Across Operation Temperature

## 9.3 System Example

### 9.3.1 External Cell Balancing

Higher cell balancing currents can be supported by means of a simple external network, as shown in Figure 11.

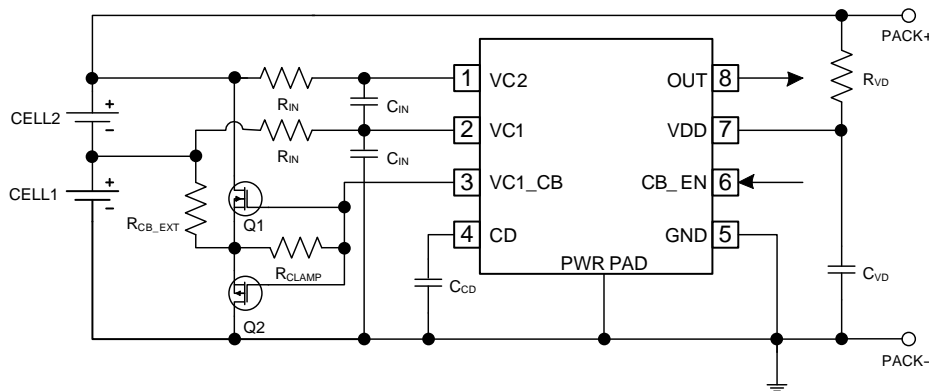


Figure 11. External Cell Balancing Configuration

$R_{\text{CLAMP}}$  ensures that both Q1 and Q2 remain off when balancing is disabled, and should be sized above 2 k $\Omega$  to prevent excessive internal device current when the balancing network is activated.  $R_{\text{CB\_EXT}}$  determines the value of the balancing current, and is dependent on the voltage of the balanced cell, as follows:

$$I_{\text{bal}} = \frac{V_{\text{CELL}}}{R_{\text{CB\_EXT}}}$$

## 10 Power Supply Recommendations

The recommended power supply for this device is a maximum 10-V operation on the VDD input pin.


## 11 Layout


### 11.1 Layout Guidelines

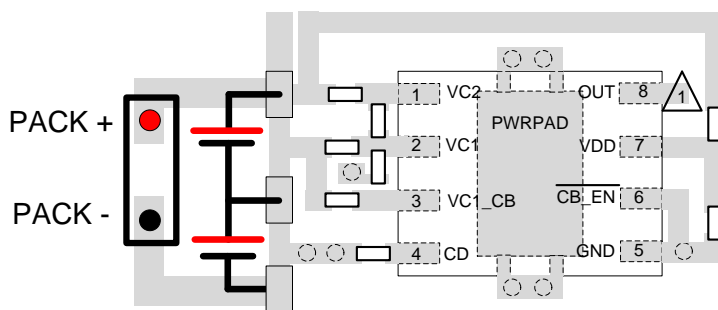
The following are the recommended layout guidelines:

1. Ensure the input filters to the VC1 and VC2 pins are as close to the IC as possible to improve noise immunity.
2. If the OUT pin is used to control a high current path, for example: to blow a chemical fuse, then care should be taken to ensure the high current path creates minimal interference of the bq29209-Q1 voltage sense inputs.
3. The input RC filter on the VDD pin should be close to the terminal of the IC.

### 11.2 Layout Example

 Additional circuitry required based on usage of the OUT pin

 Via connects between two layers



## 12 Device and Documentation Support

### 12.1 Community Resources

The following links connect to TI community resources. Linked contents are provided "AS IS" by the respective contributors. They do not constitute TI specifications and do not necessarily reflect TI's views; see TI's [Terms of Use](#).

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**Design Support** *TI's Design Support* Quickly find helpful E2E forums along with design support tools and contact information for technical support.

### 12.2 Trademarks

E2E is a trademark of Texas Instruments.  
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### 12.3 Electrostatic Discharge Caution



These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

### 12.4 Glossary

[SLYZ022](#) — *TI Glossary*.

This glossary lists and explains terms, acronyms, and definitions.

## 13 Mechanical, Packaging, and Orderable Information

The following pages include mechanical, packaging, and orderable information. This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the left-hand navigation.

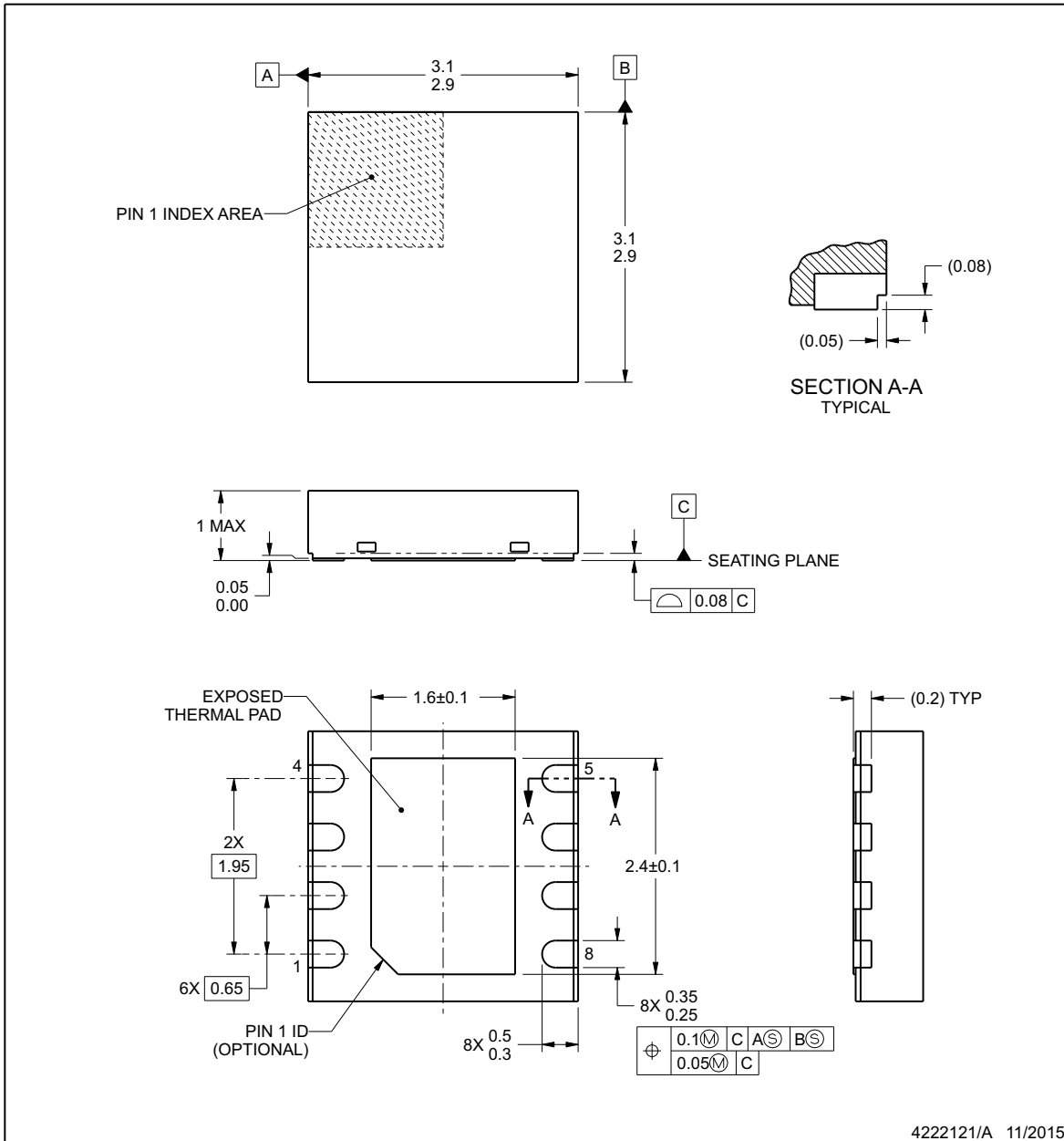


**DRB0008F**

**PACKAGE OUTLINE**

**VSON - 1 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



4222121/A 11/2015

**NOTES:**

1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
2. This drawing is subject to change without notice.
3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

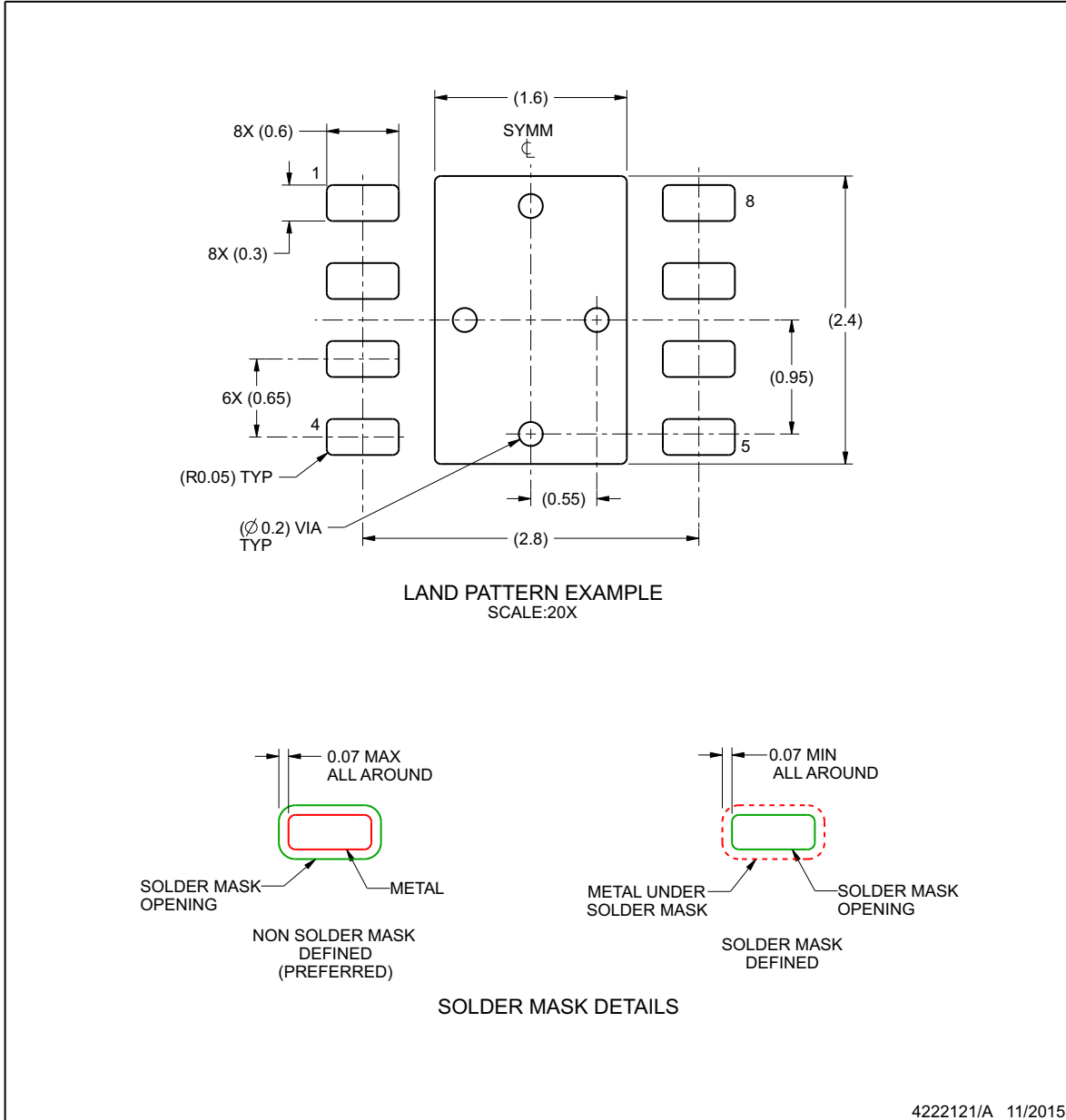


## EXAMPLE BOARD LAYOUT

### DRB0008F

### VSON - 1 mm max height

PLASTIC SMALL OUTLINE - NO LEAD



4222121/A 11/2015

NOTES: (continued)

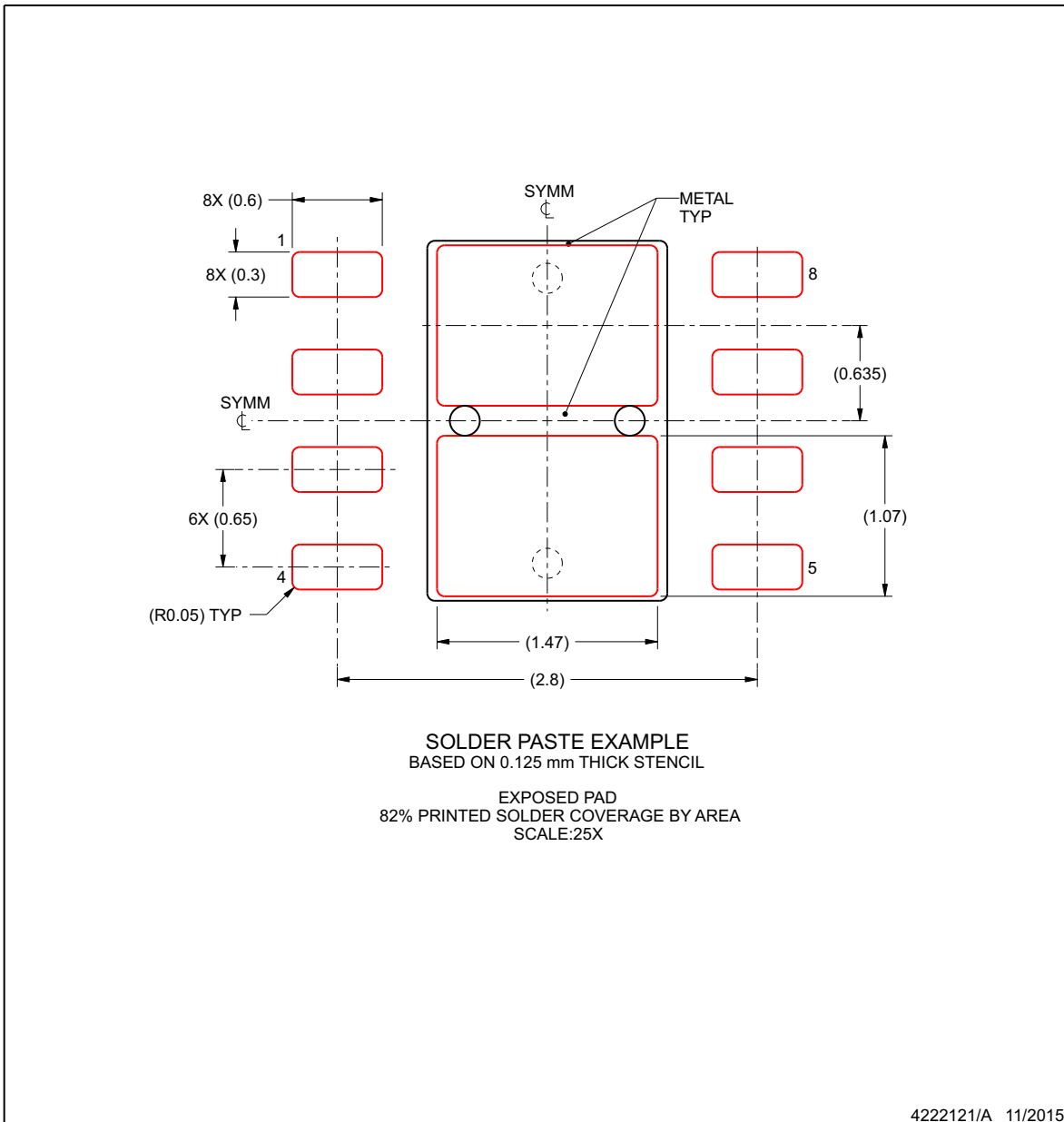
- This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 ([www.ti.com/lit/slua271](http://www.ti.com/lit/slua271)).
- Vias are optional depending on application, refer to device data sheet. If some or all are implemented, recommended via locations are shown.

**EXAMPLE STENCIL DESIGN**

**DRB0008F**

**VSON - 1 mm max height**

PLASTIC SMALL OUTLINE - NO LEAD



NOTES: (continued)

- 6. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

**PACKAGING INFORMATION**

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish (6)	MSL Peak Temp (3)	Op Temp (°C)	Device Marking (4/5)	Samples
BQ29209TDRBRQ1	ACTIVE	SON	DRB	8	3000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 105	209Q1	<a href="#">Samples</a>
BQ29209TDRBTQ1	ACTIVE	SON	DRB	8	250	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR	-40 to 105	209Q1	<a href="#">Samples</a>

(1) The marketing status values are defined as follows:

**ACTIVE:** Product device recommended for new designs.

**LIFEBUY:** TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

**NRND:** Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

**PREVIEW:** Device has been announced but is not in production. Samples may or may not be available.

**OBSELETE:** TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

**TBD:** The Pb-Free/Green conversion plan has not been defined.

**Pb-Free (RoHS):** TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

**Pb-Free (RoHS Exempt):** This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

**Green (RoHS & no Sb/Br):** TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead/Ball Finish - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead/Ball Finish values may wrap to two lines if the finish value exceeds the maximum column width.

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**OTHER QUALIFIED VERSIONS OF BQ29209-Q1 :**

- Catalog: [BQ29209](#)

**NOTE: Qualified Version Definitions:**

- Catalog - TI's standard catalog product

## TAPE AND REEL INFORMATION



### QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
BQ29209TDRBRQ1	SON	DRB	8	3000	330.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2
BQ29209TDRBTQ1	SON	DRB	8	250	180.0	12.4	3.3	3.3	1.1	8.0	12.0	Q2

**TAPE AND REEL BOX DIMENSIONS**


\*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
BQ29209TDRBRQ1	SON	DRB	8	3000	367.0	367.0	35.0
BQ29209TDRBTQ1	SON	DRB	8	250	210.0	185.0	35.0

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